Lonten N-channel 500V, 9A Power MOSFET

Description

The Power MOSFET is fabricated using the advanced planer **VDMOS** technology. The resulting device has low conduction resistance,superior switching performance and high avalanche energy.

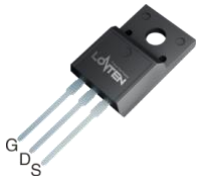
Product Summary

V_{DSS}	500V
I_D	9A
$R_{DS(on),max}$	0.8Ω
$Q_{g,typ}$	22.5 nC

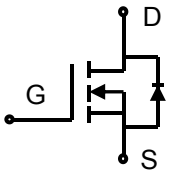
Features

- Low $R_{DS(on)}$
- Low gate charge (typ. Q_g =22.5 nC)
- 100% UIS tested
- RoHS compliant

Pin Configuration



TO-220F



N-Channel MOSFET

Applications

- Power factor correction.
- Switched mode power supplies.
- LED driver.

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	500	V
Continuous drain current (T_C = 25°C)	I_D	9	A
(T_C = 100°C)		5.2	A
Pulsed drain current [1]	I_{DM}	36	A
Gate-Source voltage	V_{GSS}	±30	V
Avalanche energy, single pulse [2]	E_{AS}	405	mJ
Power Dissipation (T_C = 25°C)	P_D	30	W
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	°C
Continuous diode forward current	I_S	9	A
Diode pulse current	$I_{S,pulse}$	36	A

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, Junction-to-case	$R_{\theta JC}$	4.1	°C/W
Thermal resistance, Junction-to-ambient[3]	$R_{\theta JA}$	65	°C/W

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube
LND9N50	TO-220F	LND9N50	50

Electrical Characteristics

T_c = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	V_{GS}=0 V, I_D=0.25 mA	500	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=0.25 mA	2	-	4	V
Drain cut-off current	I_{DSS}	V_{DS}=500 V, V_{GS}=0 V, T_j = 25°C T_j = 150°C	 - -	 -	 1 100	 μA
Gate leakage current, Forward	I_{GSSF}	V_{GS}=30 V, V_{DS}=0 V	-	-	100	nA
Gate leakage current, Reverse	I_{GSSR}	V_{GS}=-30 V, V_{DS}=0 V	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=4.5A,T_J=25℃	-	0.66	0.8	Ω
Gate resistance	R_g	V_{GS}=0V, V_{DS}=0V, f=1MHz	-	2.3	-	Ω
Dynamic characteristics						
Input capacitance	C_{iss}	V_{DS} = 25 V, V_{GS} = 0 V,	-	1063	-	
Output capacitance	C_{oss}	f = 1 MHz	-	107	-	pF
Reverse transfer capacitance	C_{rss}		-	4.7	-	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 250 V, I_D = 9A	-	12.2	-	
Rise time	t_r	R_G = 10 Ω, V_{GS}=15 V	-	11.7	-	ns
Turn-off delay time	$t_{d(off)}$		-	53.4	-	
Fall time	t_f		-	10.2	-	
Gate charge characteristics						
Gate to source charge	Q_{gs}	V_{DD}=400 V, I_D=9 A,	-	5	-	
Gate to drain charge	Q_{gd}	V_{GS}=0 to 10 V	-	8.7	-	nC
Gate charge total	Q_g		-	22.5	-	
Gate plateau voltage	$V_{plateau}$		-	5	-	V
Reverse diode characteristics						
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=9 A	-	-	1.5	V
Reverse recovery time	t_{rr}	V_R=400 V, I_F=9 A,	-	294	-	ns
Reverse recovery charge	Q_{rr}	dI_F/dt=100 A/μs	-	2.3	-	μC
Peak reverse recovery current	I_{rrm}		-	15.4	-	A

Notes:

1. Pulse width limited by maximum junction temperature.

2. VDD=60V,L=10mH, I_{AS} = 9A, Starting T_j= 25°C.

3: The value of R_{thJA} is measured by placing the device in a still air box which is one cubic foot.

Electrical Characteristics Diagrams

Figure 1. Typical Output Characteristics

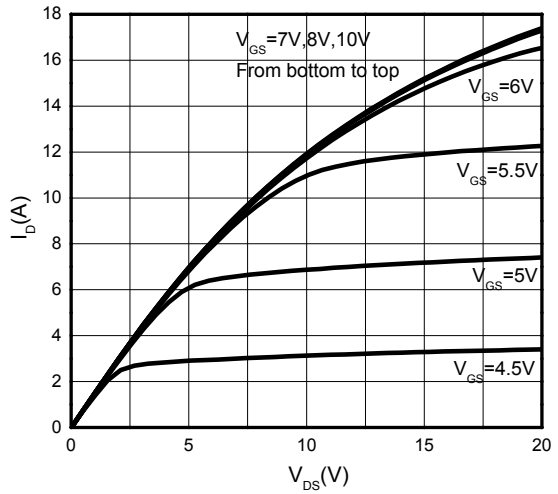


Figure 2. Transfer Characteristics

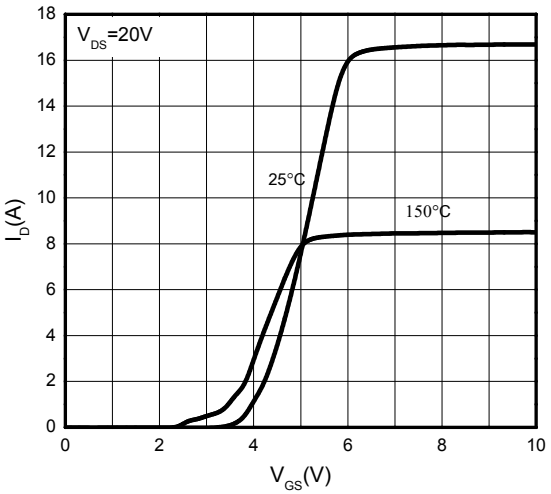


Figure 3. On-Resistance vs. Drain Current

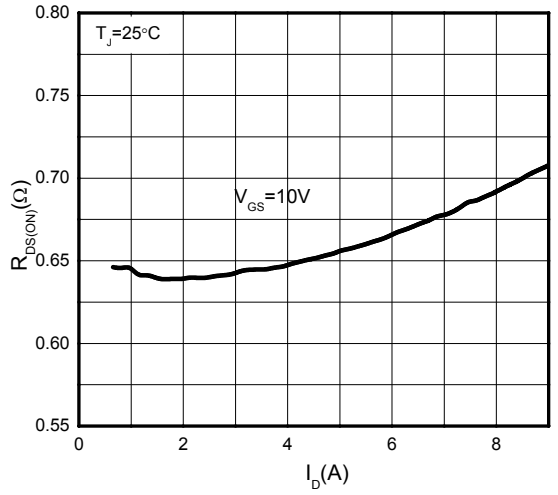


Figure 4. On-Resistance vs. Temperature

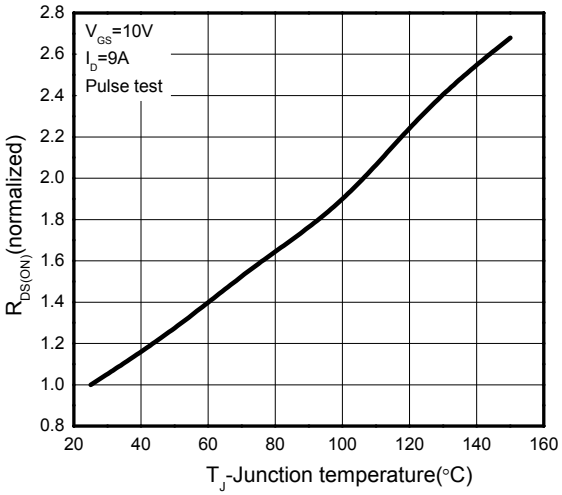


Figure 5. Breakdown Voltage vs. Temperature

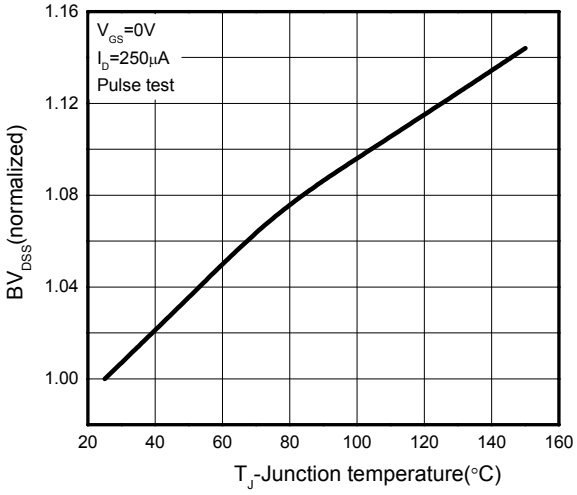


Figure 6.Threshold Voltage vs. Temperature

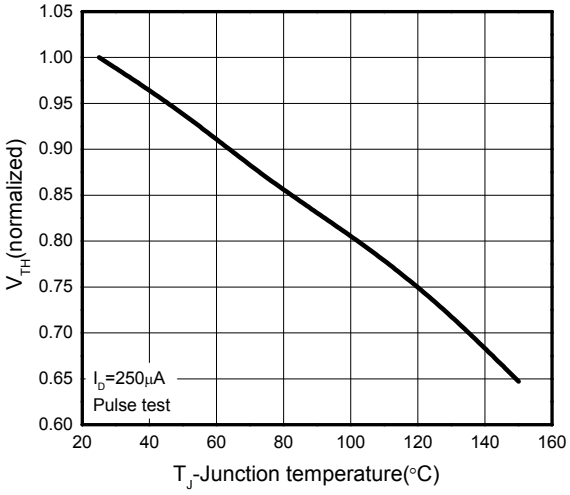


Figure 7.Rds(on) vs. Gate Voltage

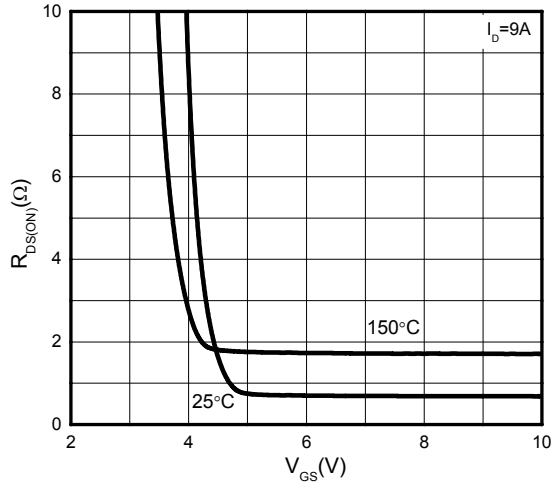


Figure 8.Body-Diode Characteristics

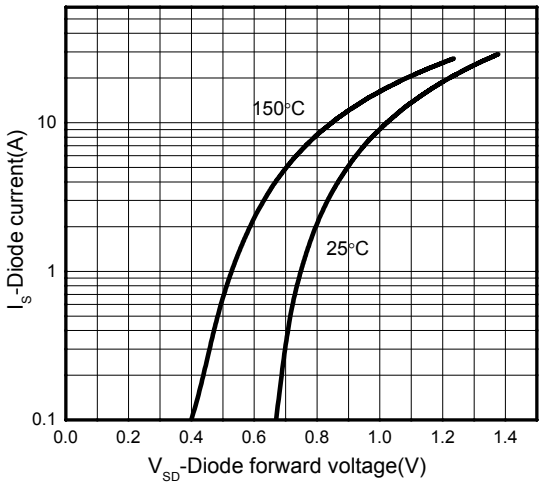


Figure 9. Capacitance Characteristics

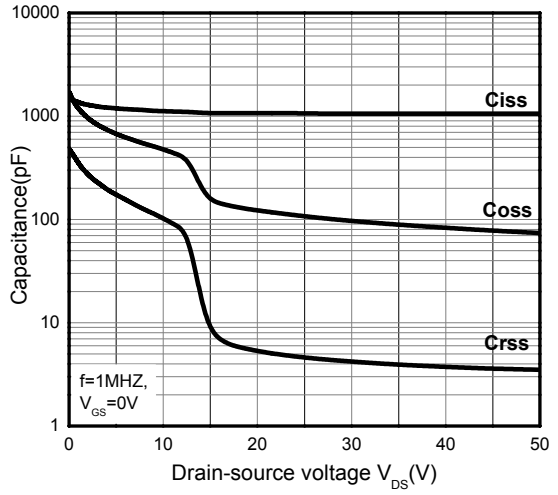


Figure 10. Gate Charge Characteristics

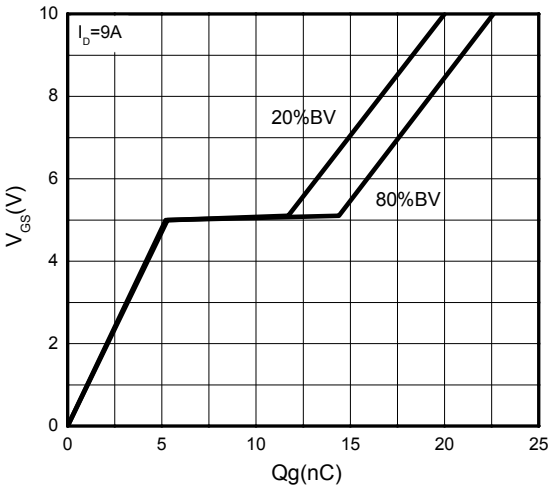


Figure 11. Continuous Drain Current vs. Temperature

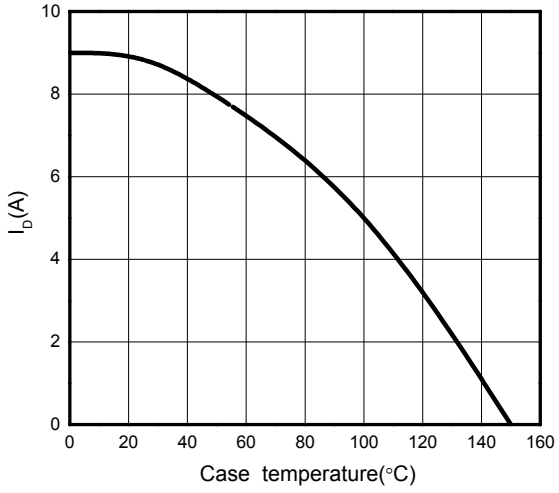


Figure 12. Power Dissipation vs. Temperatur

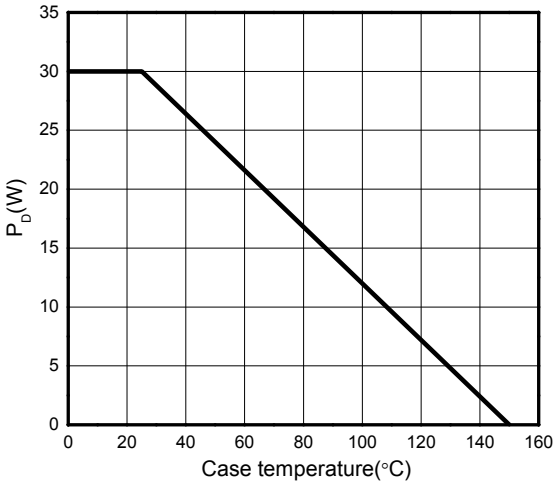


Figure 13: Safe Operating Area

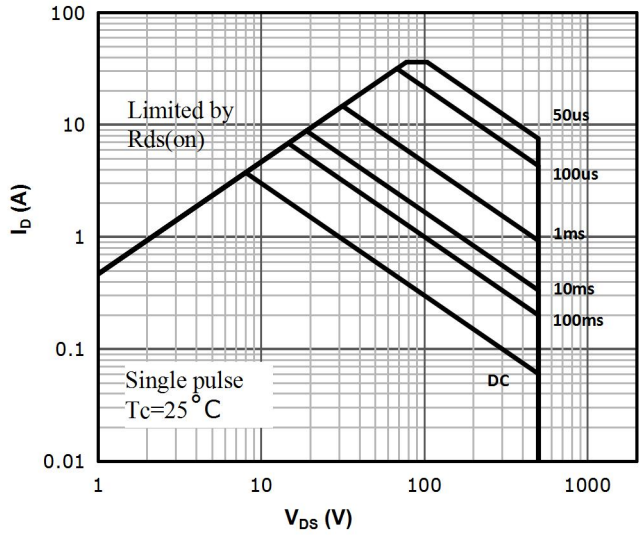
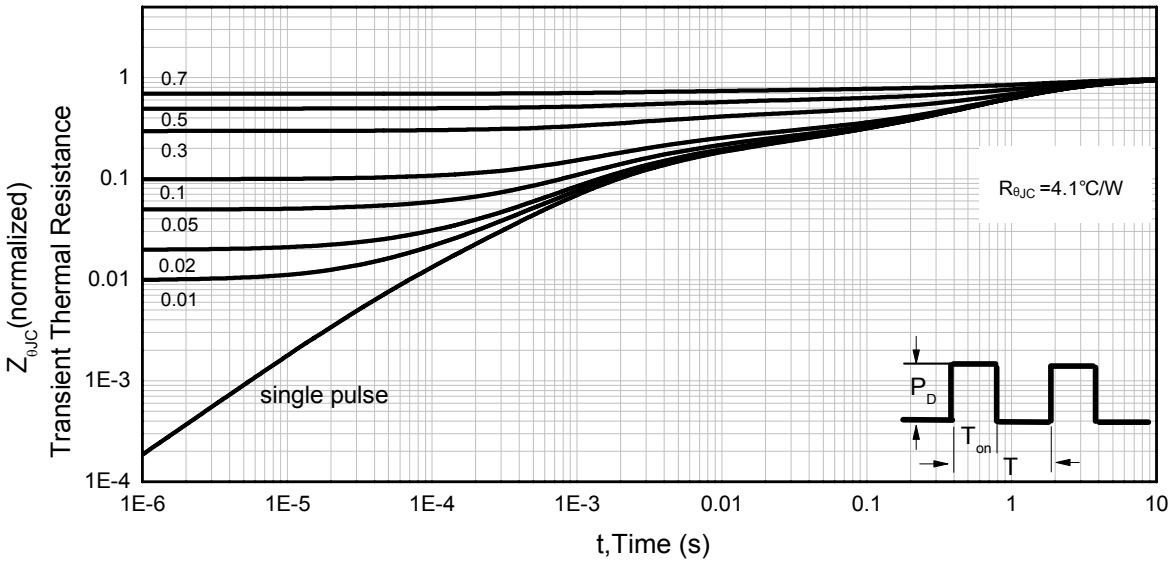
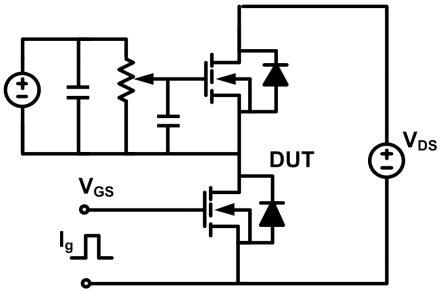


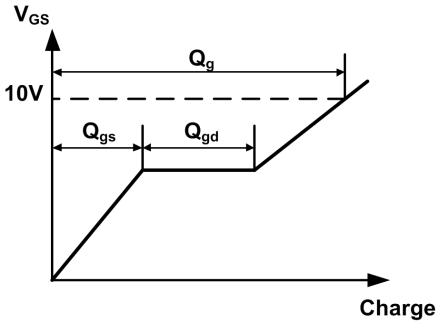
Figure 14. Transient Thermal Impedance, Junction to Case



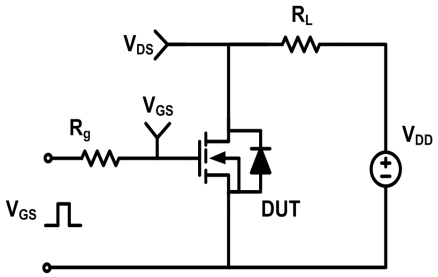
Test Circuit & Waveforms

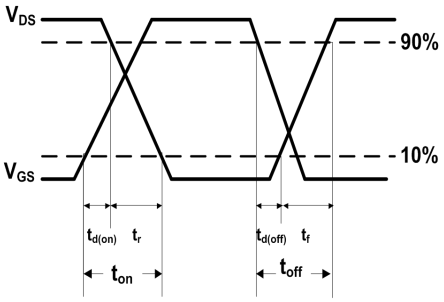
Gate Charge Test Circuit & Waveform



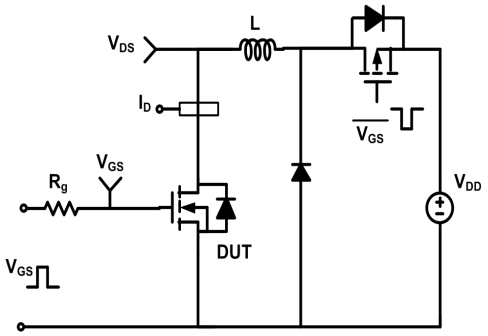


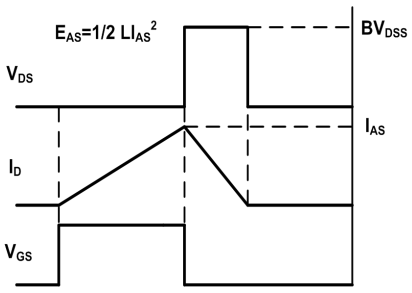
Resistive Switching Test Circuit & Waveform



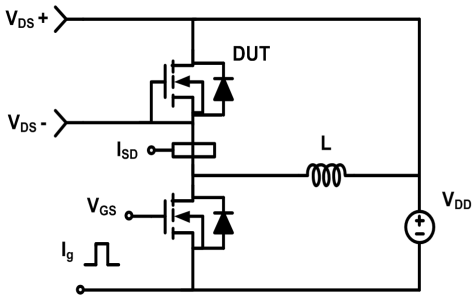


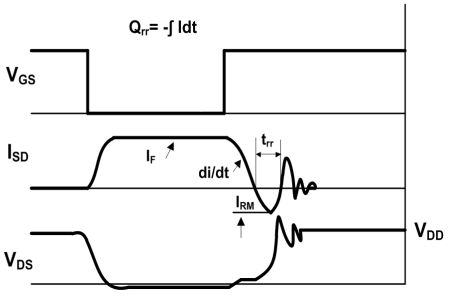
Unclamped Inductive Switching (UIS) Test Circuit & Waveform



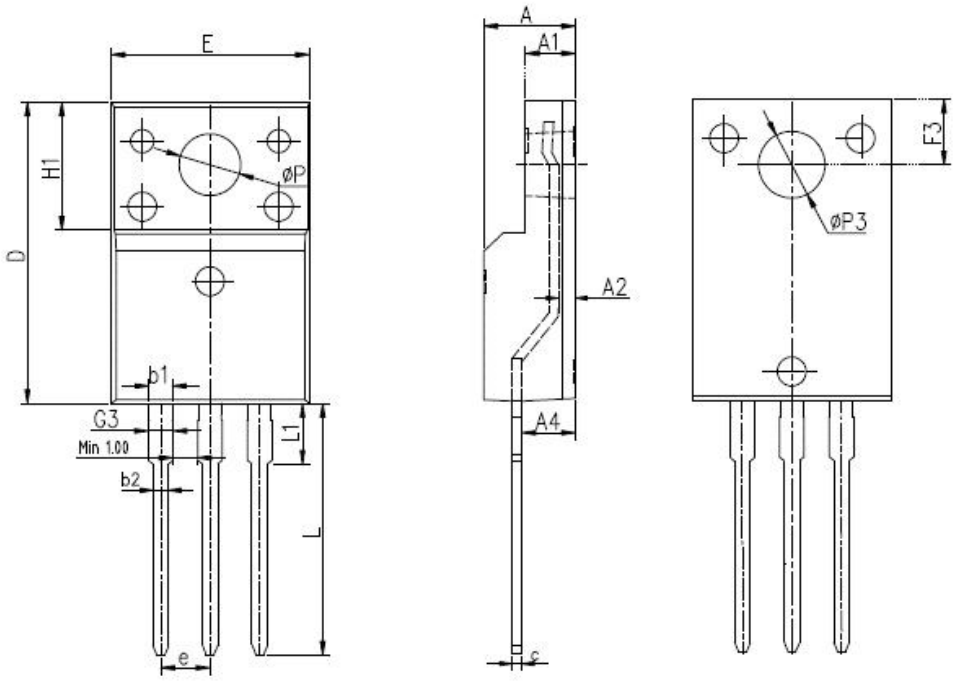


Diode Recovery Test Circuit & Waveform





Mechanical Dimensions for TO-220F



DIMENSIONS IN MILLITMETERS			DIMENSIONS IN INCHES	
SYMBOL	MIN	MAX	MIN	MAX
A	4.4	4.9	0.173	0.193
A1	2.34	2.74	0.092	0.108
A2	0.3	0.7	0.012	0.028
A4	2.5	2.96	0.098	0.117
c	0.4	0.7	0.016	0.028
D	15.57	16.4	0.613	0.646
E	9.96	10.4	0.392	0.409
H1	6.48	6.95	0.255	0.274
e	2.54BSC		0.1BSC	
L	12.64	14.2	0.498	0.559
L1	2.88	3.6	0.113	0.142
ΦP	3	3.38	0.118	0.133
ΦP3	3.15	3.65	0.124	0.144
F3	3.15	3.45	0.124	0.136
G3	1.15	1.58	0.045	0.062
b1	1.18	1.43	0.046	0.056
b2	0.7	1	0.028	0.039

Version Information

LND9N50

Revision:2020-12-17 ,Rev 0.2

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